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Deborah W. Wenocur
Deborah W. Wenocur

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Applicant: K. Sahota, D. Schonauer, J. Groschopf,)
G. Marxsen, and S. Avanzino,) Grp Art Unit: 1765
Assignee: Advanced Micro Devices, Inc.) Exam: L. Umez Eronini
Serial Number: 09/749,191)
Filed: December 26, 2000)
For: PREVENTION OF PRECIPITATION)
DEFECTS ON COPPER INTER-)
CONNECTS DURING CMP BY USE)
OF SOLUTIONS CONTAINING)
ORGANIC COMPOUNDS WITH)
SILICA ADSORPTION AND COPPER)
CORROSION INHIBITING)
PROPERTIES)

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AMENDMENT AND RESPONSE TO OFFICE ACTION

Dear Sir,

This is in response to the Final Office Action mailed on September 11, 2002. Applicant respectfully requests that this Amendment be entered and fully considered, since it responds directly to Examiner's new grounds for rejection, adds no new issues, and simplifies matters for Appeal.